

**描述 / Descriptions**

0.8A 表面贴装玻璃钝化整流桥，薄型 MBF 封装。  
0.8A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package.

**特征 / Features**

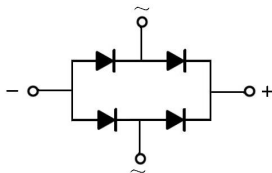
玻璃钝化芯片，反向电压：100V~1000V，正向电流：0.8A，浪涌电流大，适用于表面贴装。无卤产品。

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current:0.8 A, High Surge Current Capability, Designed for Surface Mount Application.Halogen free product.

**用途 / Applications**

一般用途。  
General purpose.

**内部等效电路 / Equivalent Circuit**

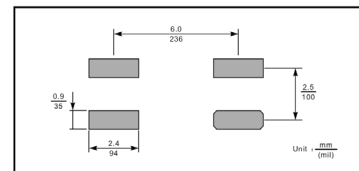


**引脚排列 / Pinning**



PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )

The recommended mounting pad size



**印章代码 / Marking**

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50°C	$I_{F(AV)}$	0.8						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	30						A
Typical Junction Capacitance <sup>1)</sup>	$C_j$	13						pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$	95						°C/W
	$R_{\theta JL}$	30						
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150						°C

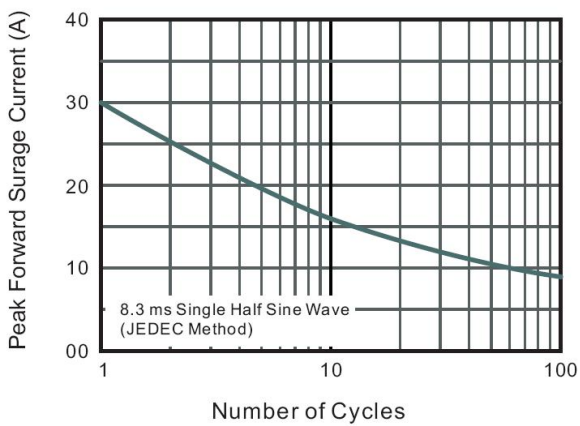
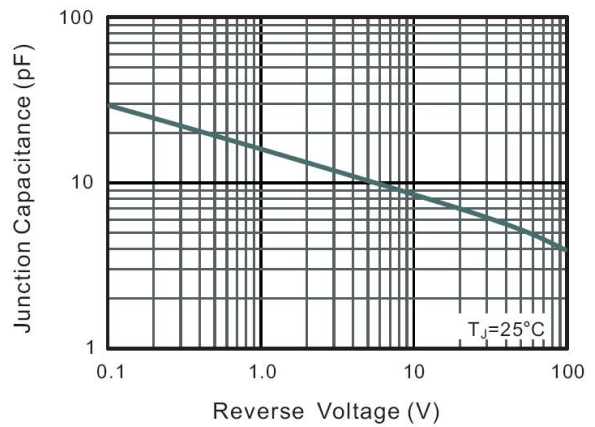
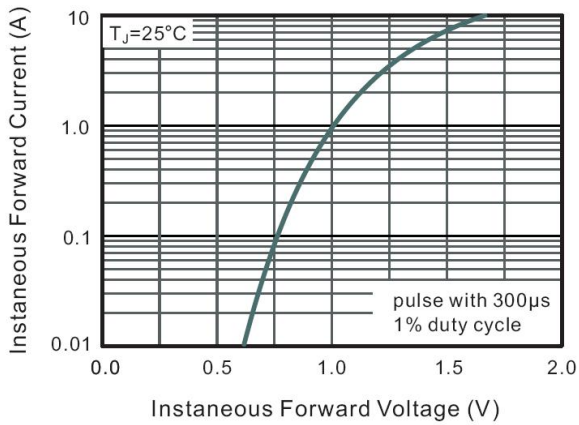
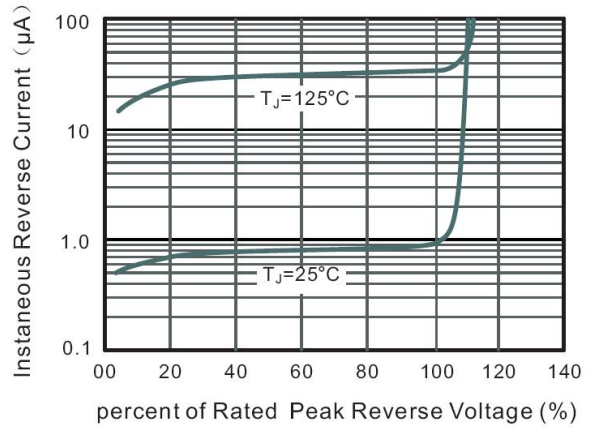
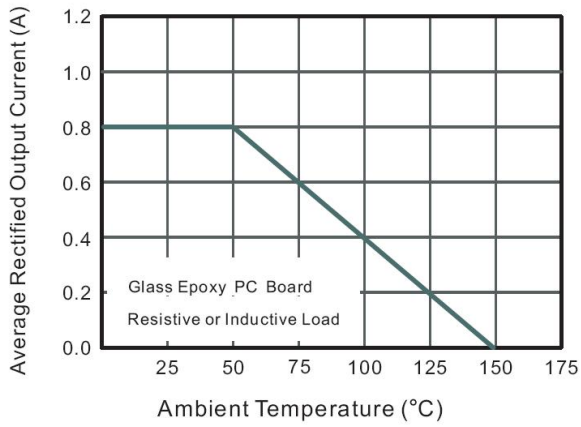
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm<sup>2</sup>) copper pad.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

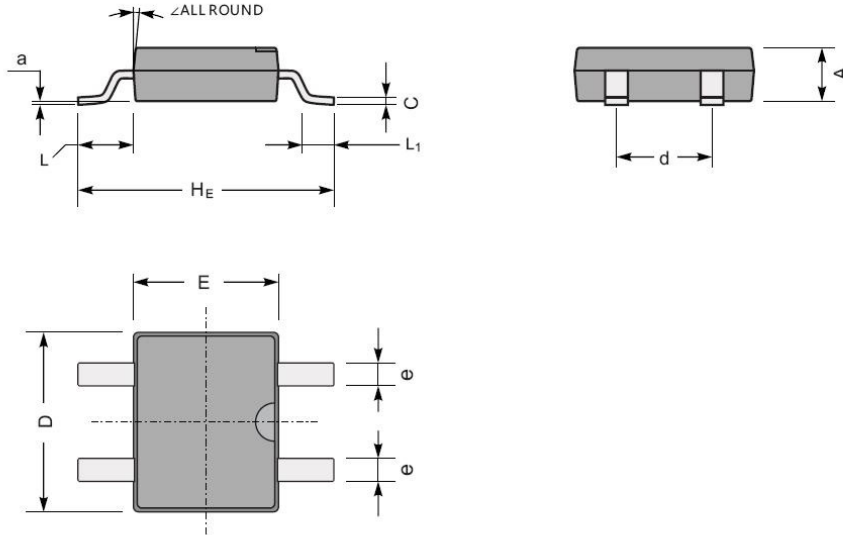
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Max Instantaneous Forward Voltage	$V_F$	$I_F=0.8A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	$I_R$	$T_a=25^\circ C$	5.0	μA
		$T_a=125^\circ C$	40	μA

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

MBF



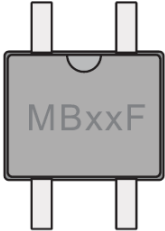
MBF mechanical data

UNIT		A	C	D	E	$H_E$	d	e	L	$L_1$	a	$\angle$
mm	max	1.6	0.22	5.0	4.1	7.0	2.7	0.7	1.7	1.1	0.2	7°
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	
mil	max	63	8.7	197	161	276	106	28	67	43	8	
	min	47	5.9	177	142	252	91	20	51	20	—	

印章说明 / Marking Instructions

### Marking

Type number	Marking code
MB1F	MB1F
MB2F	MB2F
MB4F	MB4F
MB6F	MB6F
MB8F	MB8F
MB10F	MB10F

The diagram shows a rectangular component with four pins (two on top, two on bottom). The marking 'MBxxF' is printed on the top surface of the component.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度  $25 \sim 150^\circ\text{C}$ ，时间  $60 \sim 90\text{sec}$ ；
- 2、峰值温度  $245 \pm 5^\circ\text{C}$ ，时间持续为  $5 \pm 0.5\text{sec}$ ；
- 3、焊接制程冷却速度为  $2 \sim 10^\circ\text{C}/\text{sec}$ 。

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$ , Time: $60 \sim 90\text{sec}$ .
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$ , Duration: $5 \pm 0.5\text{sec}$ .
3. Cooling Speed:  $2 \sim 10^\circ\text{C}/\text{sec}$ .

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度： $260 \pm 5^\circ\text{C}$

时间： $10 \pm 1$  sec.

Temp.: $260 \pm 5^\circ\text{C}$

Time: $10 \pm 1$  sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
MBF	5000	2	10000	5	50000	13" × 15	336X336X40	345X345X235

**使用说明 / Notices**